

## Features

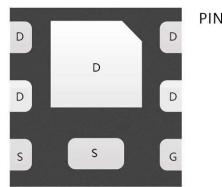
- Trench Power LV MOSFET technology
- High Power and Current handing capability
- Low Gate Charge

## Product Summary

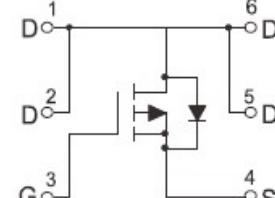
$V_{DS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
-12V	21mΩ@-4.5V	-16A
	27mΩ@-2.5V	

## Application

- PWM applications
- Power management
- Load switch



DFN2X2-6L view



Schematic diagram



1216P: Device code  
XXXX: Code  
Solid dot: Pin1 indicator

Marking and pin assignment



Halogen-Free

## Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Unit
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## Common Ratings (TC=25°C Unless Otherwise Noted)

$V_{DS}$	Drain-Source Breakdown Voltage	-12	V
$V_{GS}$	Gate-Source Voltage	±8	V
$T_J$	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$I_S$	Diode Continuous Forward Current	Tc=25°C	-16
			A

## Mounted on Large Heat Sink

$I_{DM}$	Pulse Drain Current Tested	Tc=25°C	-65	A
$I_D$	Continuous Drain Current	Tc=25°C	-16	A
$P_D$	Maximum Power Dissipation	T <sub>A</sub> =25°C	2.5	W
$R_{QJA}$	Thermal Resistance Junction-to-Ambient		50	°C/W

## Ordering Information (Example)

Type	Package	Marking	Minimum Package(pcs)	Inner Box Quantity(pcs)	Outer Carton Quantity(pcs)	Delivery Mode
MLSM1216P	DFN2X2-6L	1216P	3,000	45,000	180,000	7" reel

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
BV <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-12	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-12V, V <sub>GS</sub> =0V	--	--	-1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.4	-0.62	-1.0	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8.0A	--	13	21	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-6.2A	--	18	27	mΩ

**Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)**

C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHz	--	2100	--	pF
C <sub>OSS</sub>	Output Capacitance		--	275	--	pF
C <sub>RSS</sub>	Reverse Transfer Capacitance		--	235	--	pF

**Switching Characteristics**

Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-10V, I <sub>D</sub> =-8A, V <sub>GS</sub> =-4.5V	--	27	--	nC
Q <sub>gs</sub>	Gate Source Charge		--	4	--	nC
Q <sub>gd</sub>	Gate Drain Charge		--	7	--	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-10V, I <sub>D</sub> =-8A, V <sub>GS</sub> =-4.5V, R <sub>G</sub> =3Ω	--	9.5	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	15	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	40	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	35	--	nS

**Source- Drain Diode Characteristics**

V <sub>SD</sub>	Forward on voltage	T <sub>j</sub> =25°C, I <sub>s</sub> =-8A	--	--	-1.2	V
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### Typical Operating Characteristics

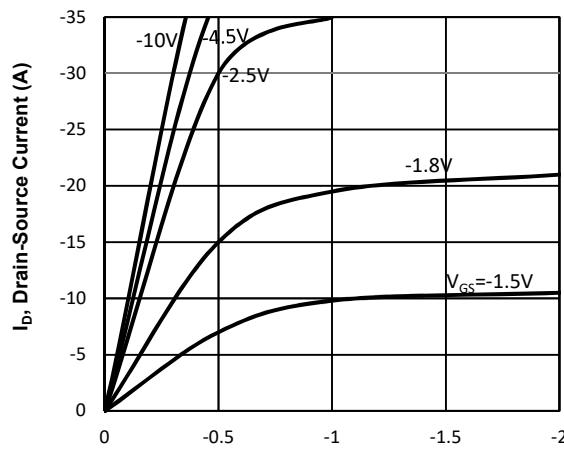


Fig1. Typical Output Characteristics

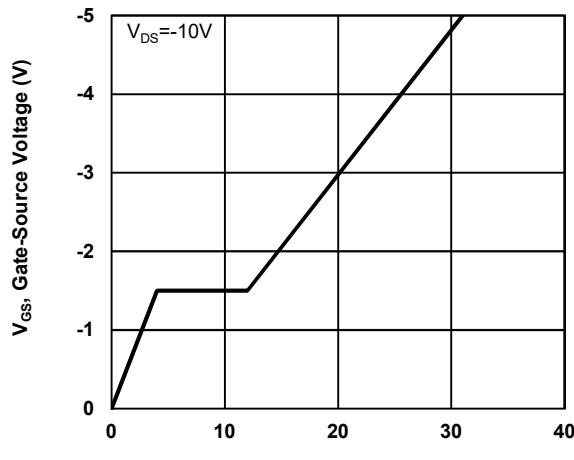


Fig2. Typical Gate Charge Vs.Gate-Source Voltage

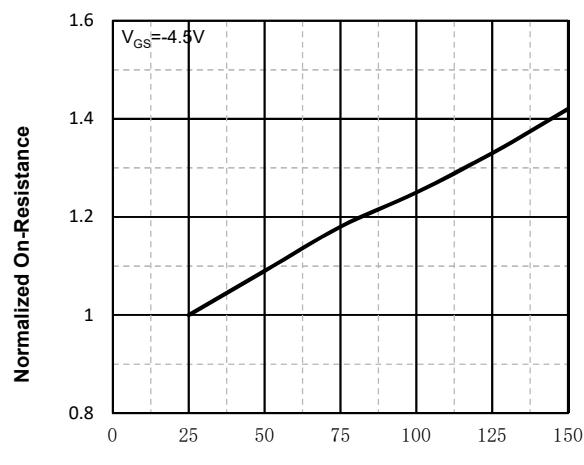


Fig3. Normalized On-Resistance Vs. Temperature

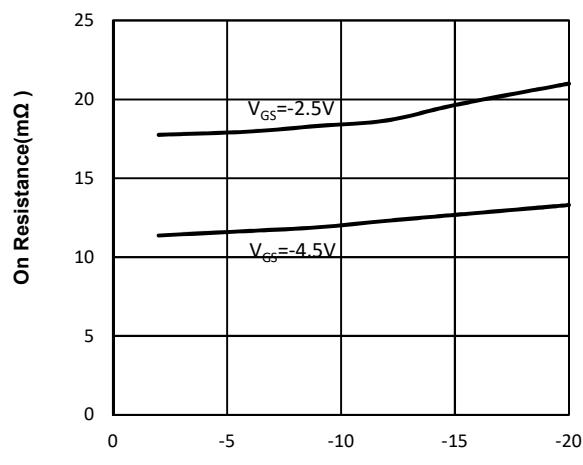


Fig4. On Resistance Vs.Drain-Source Current

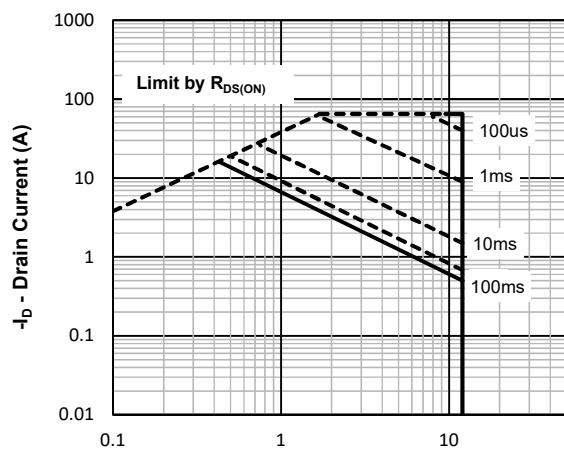


Fig5. Maximum Safe Operating Area

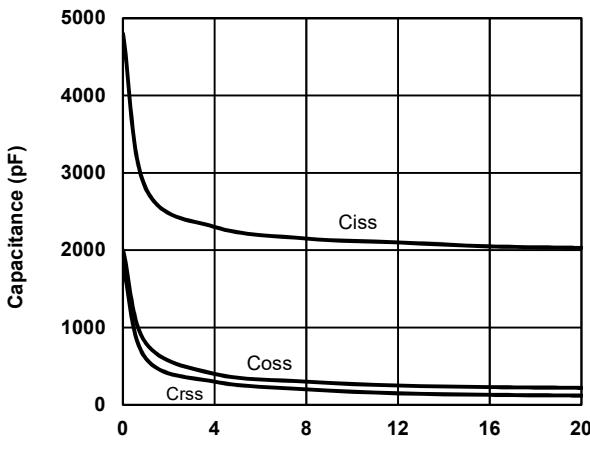
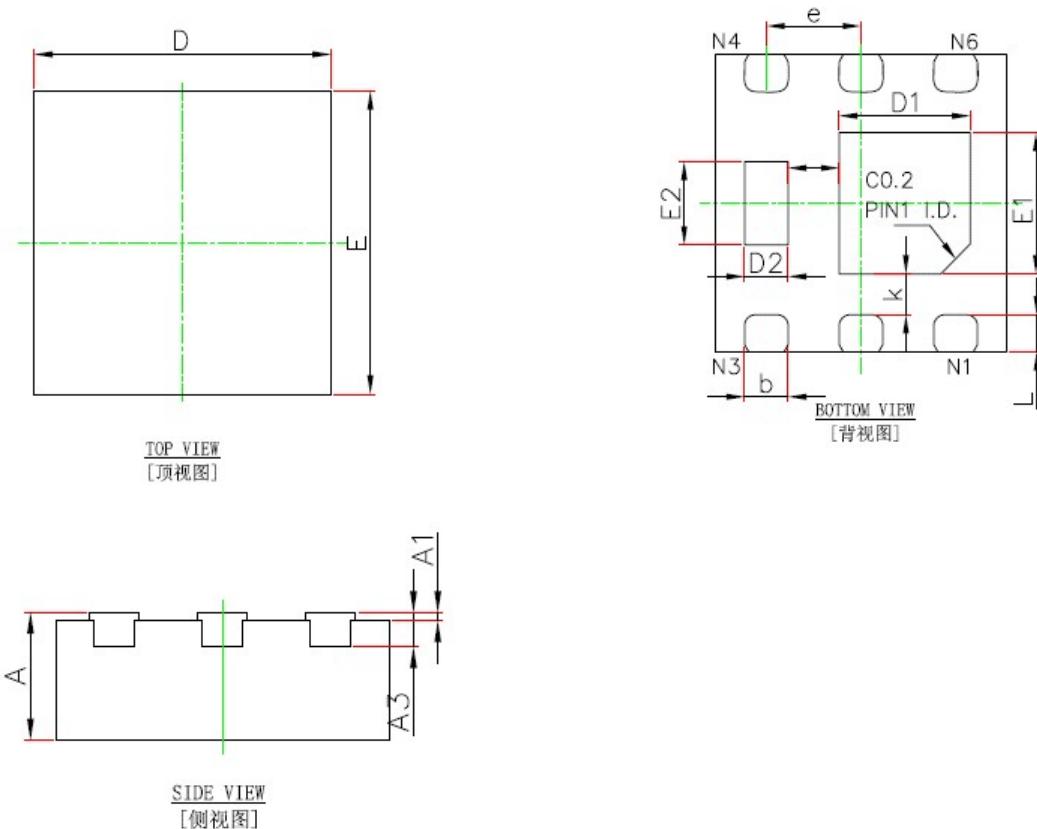


Fig6 Typical Capacitance Vs.Drain-Source Voltage

## DFN2X2-6L Package information



Symbol	Dimensions in Millimeters(mm)		Dimensions In Inches	
	Min	Max	Min	Max
A	0.600	0.700	0.023	0.027
A1	0.000	0.050	0.000	0.001
A3	0.203REF		0.007REF	
b	0.315	0.415	0.012	0.016
D	1.924	2.076	0.075	0.081
E	1.924	2.076	0.075	0.081
e	0.650TYP		0.225TYP	
L	0.224	0.376	0.008	0.014
k	0.200	-	0.007	-
E1	1.000	1.200	0.039	0.047
D1	0.900	1.100	0.035	0.043
E2	0.700	0.900	0.027	0.035
D2	0.150	0.350	0.005	0.013